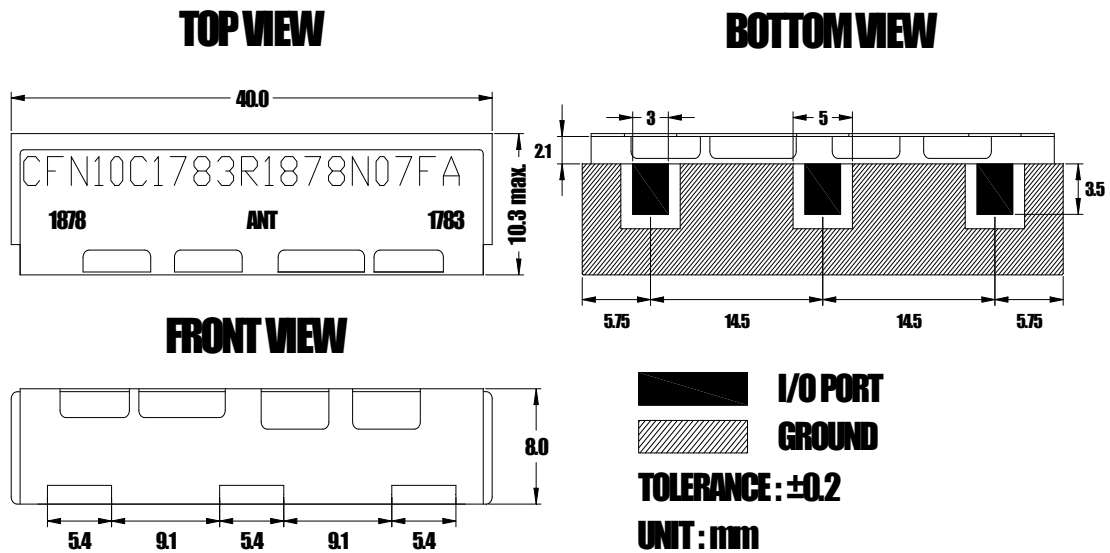


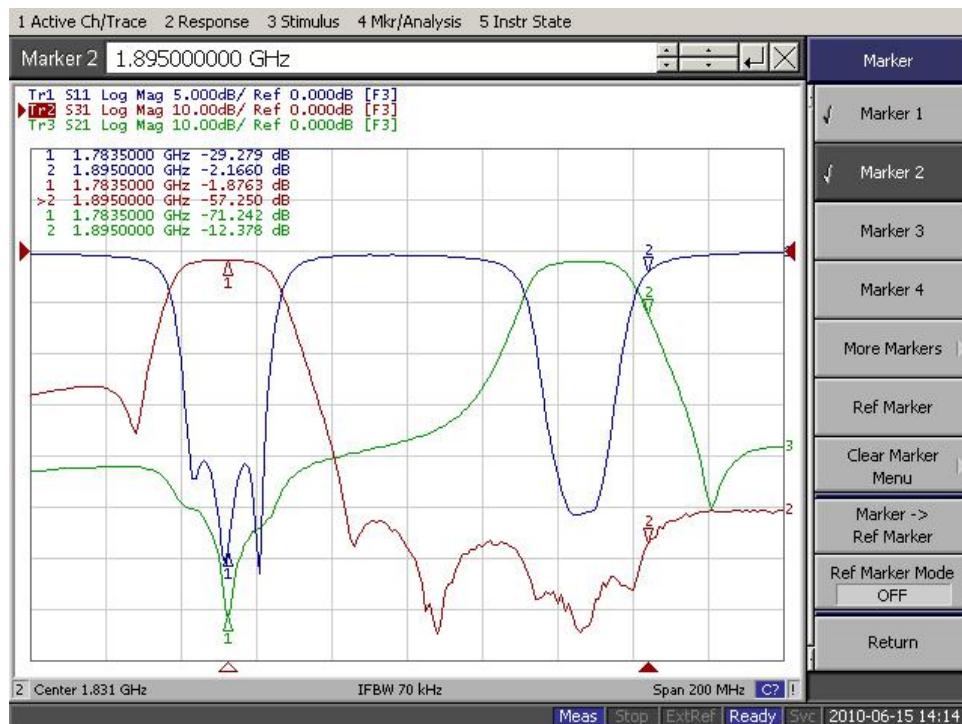
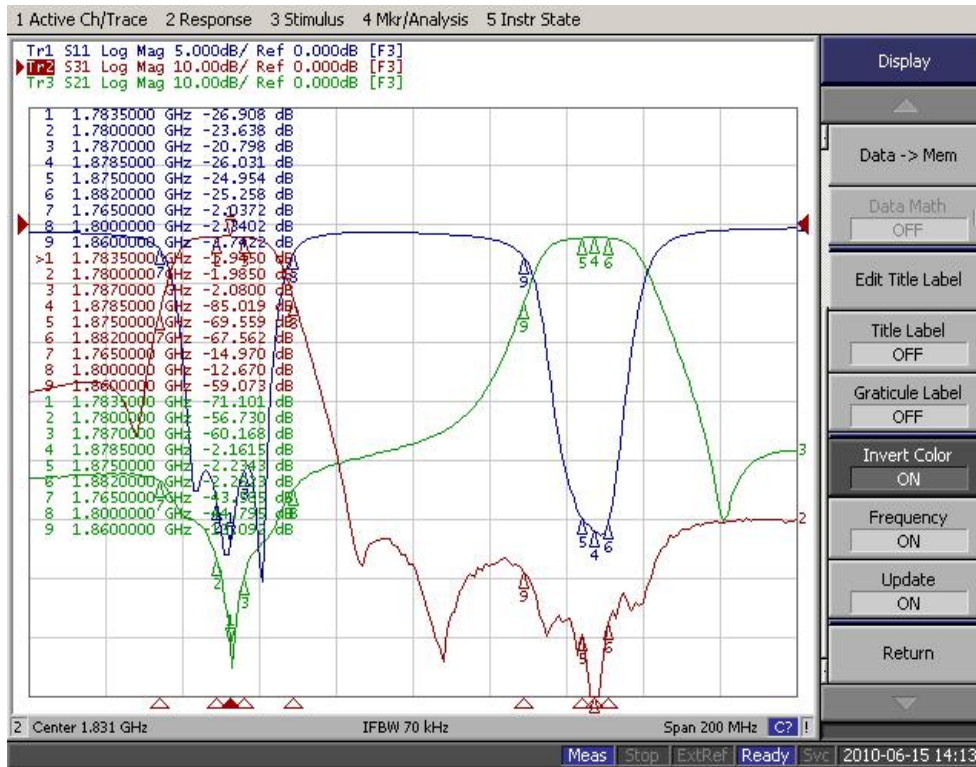
Electrical Specification

ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	1783.5	1878.5	MHz
Bandwidth [BW]	fo ±3.5 [1780.0~1787.0]	fo ±3.5 [1875.0~1882.0]	MHz
Insertion Loss in BW	3.0	3.0	dB max
Ripple in BW	2.0	2.0	dB max
Return Loss in BW	15.0	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	65.0 dBmin. @ [1875~1787]	55.0 dBmin. [1780~1787]	MHz
	10 dBmin. @ [1765 & 1800]	10.0 dBmin. [1860&1895]	MHz
	dBmin. @ [~]	dBmin.@ [~]	MHz
	dBmin. @ [~]	dBmin.@ [~]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

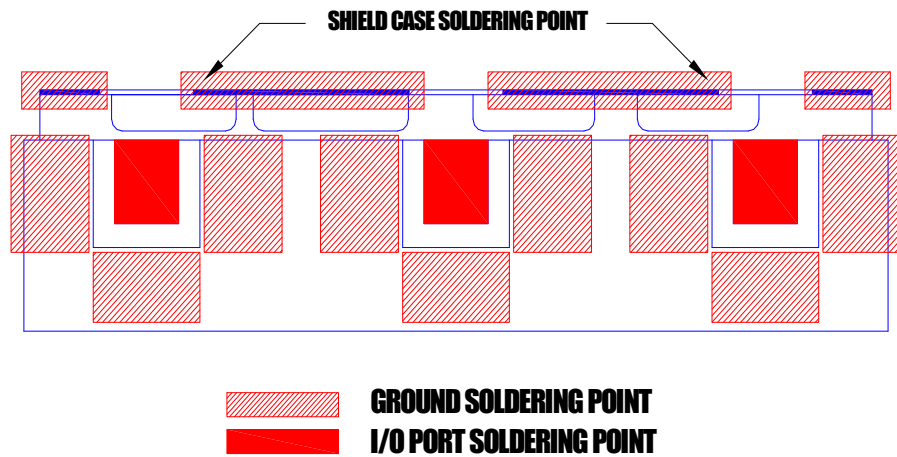
Mechanical Specification



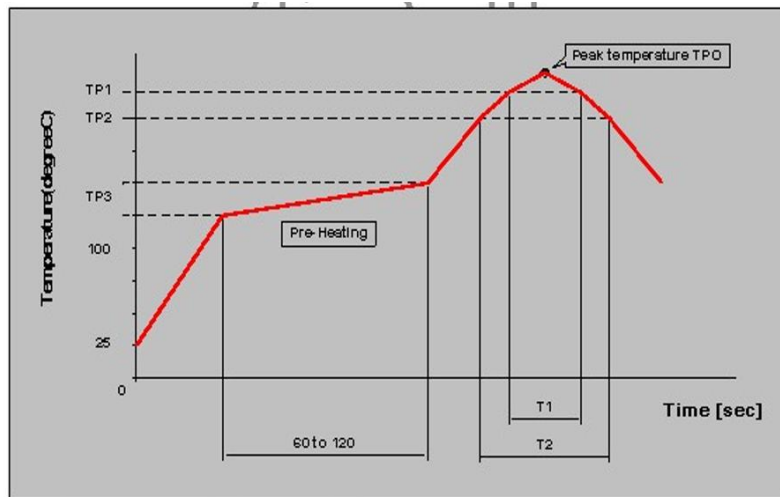
Plot Data



Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245 \pm 1.5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260 \pm 5/-0	240	20	220	70	150 to 180